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IN THE ABSTRACT:

Please add an abstract as set forth on the attached sheet.

IN THE CLAIMS:

Please amend claims 2-22, as follows:

2. (Amended) A method according to Claim 1, comprising the further step of removing regions of the layer of conductive material to define electrodes for different channels, which electrodes are electrically isolated one from another.

3. (Amended) A method according to Claim 1, comprising the further step of removing regions of the layer of conductive material to define conductive tracks which are electrically isolated one from another.

4. (Amended) A method according to Claim 3, comprising the step of removing said regions of the layer of conductive material through local vaporisation of conductive material.

5. (Amended) A method according to Claim 4, comprising the step of vaporising said conductive material through the use of a laser beam.

6. (Amended) A method according to Claim 2, wherein a land is defined between neighbouring channels on the body and the method comprising the step of removing a strip of conductive material from the land.

7. (Amended) A method according to Claim 1, comprising the step of depositing said layer in a pattern to define electrodes for different channels, which electrodes are electrically isolated one from another.

8. (Amended) A method according to Claim 1, comprising the step of depositing said layer in a pattern defining a plurality of said conductive tracks which are electrically isolated one from another.

9. (Amended) A method according to Claim 7, comprising the step of achieving patterning of the deposited conductive layer through the use of masking.

10. (Amended) A method according to Claim 1, comprising the step of attaching the body to the base prior to formulation of the channels in the body.

11. (Amended) A method according to Claim 10, comprising the step of forming the channels by removing regions of the body.

12. (Amended) A method according to Claim 11, wherein the step of removing regions of the body defines discrete walls of piezoelectric material, separated one from each other.

13. (Amended) A method according to Claim 11, wherein the step of removing regions of the body also removes regions of the base.

14. (Amended) A method according to Claim 1, comprising the step of chamfering the body adjacent the base to provide regions of the deposited layer of conductive material which overlie the body and the base respectively and which meet at an obtuse angle.

15. (Amended) A method according to Claim 1, comprising the step of attaching the body to the base through adhesive, there being defined between the body and the base a fillet of said adhesive which serves as a key for the deposited layer of conductive material.

16. (Amended) A component for a droplet deposition apparatus comprising a body of piezoelectric material formed with a plurality of channels, each channel having a channel surface; and a separate base having a base surface free of substantial discontinuities; wherein the body is attached to said base surface and a layer of conductive material extends continuously over said channel surfaces of and said base surface, thereby defining an electrode on each channel surface and a conductive track connected thereto on the base surface.

17. (Amended) A component according to Claim 16, comprising an integrated circuit carried on the base, said conductive tracks providing electrical interconnection between the electrodes and the integrated circuit.

18. (Amended) A component according to Claim 16, wherein the base surface is substantially planar.

19. (Amended) A component according to Claim 16, wherein the body abuts the base at an obtuse angle.

20. (Amended) A component according to Claim 16, wherein the base is formed of a material selected from the group consisting of aluminium nitride, alumina, invar and glass.

21. (Amended) A component according to Claim 16, wherein the conductive material is selected from the group consisting of copper, nickel, gold, and alloys thereof.

22. (Amended) A component according to Claim 16, wherein the conductive material is deposited through electroless plating.

Please add new claims 23-25, as follows:

23. A method according to Claim 2, comprising the further step of removing regions of the layer of conductive material to define conductive tracks which are electrically isolated one from another.

24. A method according to Claim 23, comprising the step of removing said regions of the layer of conductive material through local vaporisation of conductive material.

25. A method according to Claim 24, comprising the step of vaporising said conductive material through the use of a laser beam.

REMARKS

By the foregoing amendments to the specification, a cross-reference to the parent international application has been provided and the claims have been amended to better conform to U.S. practice and to omit multiple dependencies. New claims 23-25 find support in original claims 3-5.

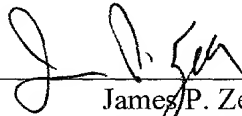
The filing fee has been calculated based on the claims as amended above. No new matter has been added.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

Please amend claims 2-22, as follows:

2. (Amended) A method according to Claim 1, comprising the further step of removing regions of the layer of conductive material to define electrodes for different channels, which electrodes are electrically isolated one from another.

3. (Amended) A method according to Claim 1 [or Claim 2], comprising the further step of removing regions of the layer of conductive material to define conductive tracks which are electrically isolated one from another.

4. (Amended) A method according to [Claim 2 or] Claim 3, [wherein] comprising the step of removing said regions of the layer of conductive material [are removed] through local vaporisation of conductive material.

5. (Amended) A method according to Claim 4, [wherein] comprising the step of vaporising said conductive material [is vaporised] through the use of a laser beam.

6. (Amended) A method according to [any one of Claims] Claim 2 [to 5], wherein a land is defined between neighbouring channels on the body and the method comprising the step of removing a strip of conductive material [is removed] from [a] the land [on the body which is defined between neighbouring channels].

7. (Amended) A method according to Claim 1, [wherein] comprising the step of depositing said layer [is deposited] in a pattern to define electrodes for different channels, which electrodes are electrically isolated one from another.

8. (Amended) A method according to Claim 1 [or Claim 7], [wherein] comprising the step of depositing said layer [is deposited] in a pattern defining a plurality of said conductive tracks which are electrically isolated one from another.

9. (Amended) A method according to Claim 7 [or Claim 8, wherein], comprising the step of achieving patterning of the deposited conductive layer [is achieved] through the use of masking.

10. (Amended) A method according to [any one of the preceding claims, wherein] Claim 1, comprising the step of attaching the body [is attached] to the base prior to formulation of the channels in the body.

11. (Amended) A method according to Claim 10, [wherein] comprising the step of forming the channels [are formed through removal of] by removing regions of the body.

12. (Amended) A method according to Claim 11, wherein the step of removing regions of the body [serves to define] defines discrete walls of piezoelectric material, separated one from each other.

13. (Amended) A method according to Claim 11 [or Claim 12], wherein the step of removing regions of the body [serves] also [to remove] removes regions of the base.

14. (Amended) A method according to [any one of the preceding claims, wherein] Claim 1, comprising the step of chamfering the body [is chamfered] adjacent the base [so as] to provide regions of the deposited layer of conductive material which overlie the body and the base respectively and which meet at an obtuse angle.

15. (Amended) A method according to [any one of the preceding claims, wherein] Claim 1, comprising the step of attaching the body [is attached] to the base through adhesive, there being defined between the body and the base a fillet of said adhesive which serves as a key for the deposited layer of conductive material.

16. (Amended) A component for a droplet deposition apparatus comprising a body of piezoelectric material formed with a plurality of channels, each channel having a channel surface; and a separate base having a base surface free of substantial discontinuities; wherein the body is attached to said base surface and a layer of conductive material extends continuously over said channel surfaces of and said base surface, thereby defining an electrode on each channel surface and a conductive track connected thereto on the base surface.

17. (Amended) A component according to Claim 16, [wherein]
comprising an integrated circuit [is] carried on the base, said conductive tracks
[serving to provide] providing electrical interconnection between the electrodes and
the integrated circuit.

18. (Amended) A component according to Claim 16 [or Claim 17],
wherein the base surface is substantially planar.

19. (Amended) A component according to [any one of Claims] Claim
16 [to 18], wherein the body abuts the base at an obtuse angle.

20. (Amended) A component according to [any one of Claims] Claim
16 [to 19], wherein the base is formed of a material selected from the group consisting
of aluminium nitride, alumina, invar [or] and glass.

21. (Amended) A component according to [any one of Claims] Claim
16 [to 20], wherein the conductive material is selected from the group consisting of
copper, nickel, gold, and alloys thereof.

22. (Amended) A component according to [any one of Claims] Claim
16 [to 21], wherein the conductive material is deposited through electroless plating.

Please add new claims 23-25, as follows:

23. A method according to Claim 2, comprising the further step of removing regions of the layer of conductive material to define conductive tracks which are electrically isolated one from another.

24. A method according to Claim 23, comprising the step of removing said regions of the layer of conductive material through local vaporisation of conductive material.

25. A method according to Claim 24, comprising the step of vaporising said conductive material through the use of a laser beam.